221. Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per the Label Table in the PDF schematic.

222. These assemblies are ESD sensitive, ESD precautions shall be observed.

223. These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

224. These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.

ASSEMBLY VARIANT: 001

<table>
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<th>PCB VIEWED FROM TOP SIDE</th>
<th>BOARD #: TIDA-01069</th>
<th>REV: E1</th>
<th>SUN REV: Not In VersionControl</th>
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PLOT NAME = Top Assembly Drawing

GENERATED: 28/02/2017 11:10:50

TEXAS INSTRUMENTS
COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: 001

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<th>PCB VIEWED FROM BOTTOM SIDE</th>
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| PLOT NAME = Bottom Assembly Drawing | GENERATED : 28/02/2017 11:10:51 | TEXAS INSTRUMENTS |
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